

PETLIN (MALAYSIA) SDN BHD (478535-T)

PRODUCT DATA SHEET



PETLIN LD C225Y Low Density Polyethylene

PETLIN LD C225Y is a low density polyethylene resin for high clarity general purpose film applications. It is produced by the state-of-the-art DSM Stamicarbon tubular process. It contains antioxidant (BHT free), slip and antiblock additives. It is intended primarily for blown film process.

Characteristics : low gels, high clarity, high gloss, good sealability, medium slip, high antiblocking.

Applications : films for : textile, garment ; carrier bags ; bubble films ; zip bags.

Recommended gauges : 20 - 100 microns

Extrusion Conditions : for blown film : melt temperature 150-170°C , recommended blow-up-ratio of 2 to 3 : 1

Typical Data : (25 microns film)

Properties	Units	Typical values	Test methods
<u>Polymer properties :</u>			
Melt Flow Rate:	dg/min	2.5	ISO 1133
Density	kg/m ³	921	ISO 1183 (A)
<u>Optical properties :</u>			
Gloss (45°)	%	63	ASTM D2457
Haze	%	7.0	ASTM D1003A
<u>Mechanical properties :</u>			
Impact strength	g	83	ASTM D1709
Tear strength	TD kN/m	30	ISO 6383-2
	MD kN/m	80	
Tensile stress at break	TD N/mm ²	16.5	ISO R527-3
	MD N/mm ²	29.5	
Strain at break	TD %	624	ISO R527-3
	MD %	116	
Modulus of elasticity	TD N/mm ²	232	ISO R527-3
	MD N/mm ²	215	
Coefficient of friction	-	0.1	ASTM D1894

The properties shown above are typical values and are not to be taken as specifications.

Food contact approval status :

This material complies with FDA 21 CFR 177.1520 when used unmodified and according to good manufacturing practices for food contact applications. Accordingly, this material may be used in all food contact applications.

IMPORTANT NOTICE :

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